



IN THE UNITED STATES PATENT & TRADEMARK OFFICE

Appl. No. : 10/694,104 Confirmation No.: 3099
Applicant : Glen E. Leinbach
Filed : October 27, 2003
TC/A.U. : 2826
Examiner : Kevin V. Quinto
Docket No. : 10031010-1
Title : Method and Apparatus for Improving Defective Solder Joint
Detection Using X-ray Inspection of Printed Circuit Assemblies

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

AMENDMENT AND RESPONSE

Sir:

In response to the non-final Office Action mailed June 30, 2004, please enter the following amendments in the above-identified patent application. Claims 4-6 and 7-9 are now pending in the present patent application. Reconsideration and allowance of the application and presently pending claims, as amended herein, are respectfully requested.

Amendments to the Claims are reflected in the listing of claims, which begin on page 2 of this paper.

Remarks begin on page 4 of this paper.